

Ensuring Halide Free PCB's do not Cause Signal Integrity Problems

iNEMI HF Signal Integrity WG Kickoff

02-18-2009



Report out first 1st FTF

- Participants
 - Cisco
 - Dell
 - Intel
- High level strategy agreed upon
 - Step 1: Simulations to assess and define the critical parameters, values and the range
 - Step 2: Define a common measurement methodology so the parameters in step 1 can be characterized for current HF materials
 - Step 3: Map existing materials against the critical parameter values ... possibly use a third party test house
 - Step 4: Provide validation data of real systems baselined against FR4
 - Step 5: Communicate electrical needs to material suppliers
- Schedule TBD – Weekly meetings to begin within the next few weeks.

